

# Logic Packaging Migration

Pin	SOIC	SOP	SSOP	QSOP	TSSOP	VSSOP	TVSOP	SOT	BGA	QFN	WCSP
5								 			
6								 			
8	 D	 PS	 DCT		 PW	 DCU					
14	 D	 NS	 DB		 PW		 DGV			 RGY	
16	 D  DW	 NS	 DB	 DBQ	 PW		 DGV			 RGY	
20	 DW	 NS	 DB	 DBQ	 PW		 DGV		 VFBGA <sup>††</sup>  GQN/ZQN	 RGY	
24	 DW	 NS	 DB	 DBQ	 PW		 DGV				
28	 DW		 DL		 PW						
48			 DL		 DGG		 DGV		 VFBGA <sup>††</sup>  GQL/ZQL		
56			 DL		 DGG		 DGV		 VFBGA <sup>††</sup>  GQL/ZQL		
64					 DGG						
80							 DBB				
96									 LFBGA <sup>††</sup>  GKE/ZKE		
114									 LFBGA <sup>††</sup>  GKF/ZKF		

[logic.ti.com](http://logic.ti.com)

<sup>†</sup>WCSP is the Industry Standard reference for DSBGA which includes the NanoStar™ (YEA) and NanoFree™ (YZA) packages

<sup>††</sup>VFBGA represents the MicroStar Jr™ packages and LFBGA identifies the MicroStar BGA package™ "Z" indicates Lead-Free Option